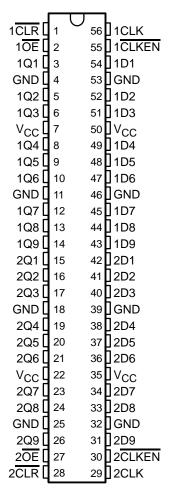
- Members of the Texas Instruments Widebus ™ Family
- Provides Extra Data Width Necessary for Wider Address/Data Paths or Buses With Parity
- Flow-Through Architecture Optimizes
  PCB Layout
- Distributed V<sub>CC</sub> and GND Pin Configuration Minimizes High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1-µm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Pin Spacings

#### description

These 18-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing wider buffer registers, I/O ports, parity bus interfacing, and working registers.

The 'AC16823 can be used as two 9-bit flip-flops or one 18-bit flip-flop. With the clock-enable (CLKEN) input low, the D-type flip-flops enter data on the low-to-high transitions of the clock. Taking CLKEN high disables the clock buffer, thus latching the outputs. Taking the clear (CLR) input low causes the Q outputs to go low independently of the clock.

54AC16823 . . . WD PACKAGE 74AC16823 . . . DL PACKAGE (TOP VIEW)



The output enable  $(\overline{OE})$  input can be used to place the outputs in either a normal logic state (high or low) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly.

OE does not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The 74AC16823 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54AC16374 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74AC16823 is characterized for operation from –40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

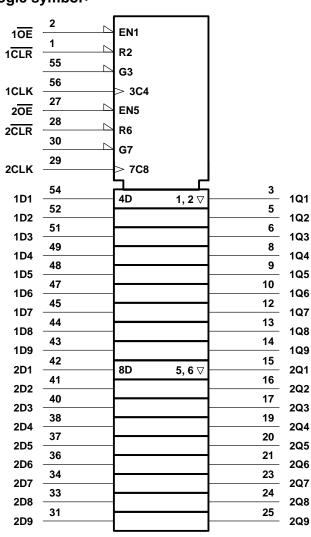
EPIC and Widebus are trademarks of Texas Instruments Incorporated.



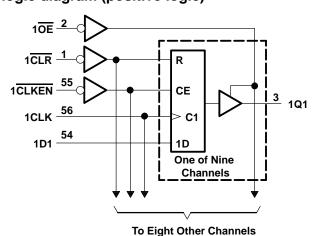
## FUNCTION TABLE (each 9-bit stage)

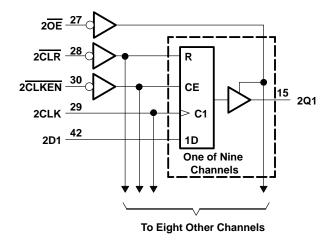
	INPUTS							
OE	CLR	CLKEN	CLK	D	Q			
L	L	Х	Χ	Х	L			
L	Н	L	$\uparrow$	Н	Н			
L	Н	L	$\uparrow$	L	L			
L	Н	L	L	Х	$Q_0$			
L	Н	Н	Χ	Х	$Q_0$			
Н	Χ	X	Χ	Х	Z			

### logic symbol†



## logic diagram (positive logic)







<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	$0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, V <sub>O</sub> (see Note 1)	$0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ )	±20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ )	±50 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±50 mA
Continuous current through V <sub>CC</sub> or GND	±450 mA
Maximum power package dissipation at T <sub>A</sub> = 55°C (in still air)(see Note 2): DL package	: 1.4 W
Storage temperature range, T <sub>stq</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions (see Note 3)

			54	AC1682	:3	74	AC1682	:3	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		3	5	5.5	3	5	5.5	V
		VCC = 3 V	2.1			2.1			
$V_{IH}$	High-level input voltage	$V_{CC} = 4.5 \text{ V}$	3.15			3.15			V
		$V_{CC} = 5.5 \text{ V}$	3.85			3.85			
		V <sub>CC</sub> = 3 V			0.9			0.9	
V <sub>IL</sub>	Low-level input voltage	$V_{CC} = 4.5 \text{ V}$		3	1.35			1.35	V
		$V_{CC} = 5.5 \text{ V}$		P	1.65			1.65	
٧ <sub>I</sub>	Input voltage		0	1	VCC	0		VCC	V
٧o	Output voltage		0	3	VCC	0		VCC	V
		V <sub>CC</sub> = 3 V		)"	-4			-4	
loh	High-level output current	$V_{CC} = 4.5 \text{ V}$	Q		-24			-24	mA
		$V_{CC} = 5.5 \text{ V}$			-24			-24	
		VCC = 3 V			12			12	
loL	Low-level output current	V <sub>CC</sub> = 4.5 V			24			24	mA
		V <sub>CC</sub> = 5.5 V			24			24	
Δt/Δν	Input transition rise or fall rate		0		10	0		10	ns/V
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>2.</sup> The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

### 54AC16823, 74AC16823 18-BIT BUS INTERFACE FLIP-FLOPS WITH 3-STATE OUTPUTS

SCAS243A - APRIL 1991 - REVISED APRIL 1996

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER	TEST CONDITIONS	V	T.	A = 25°C	;	54AC1	6823	74AC16823		UNIT
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
		3 V	2.9			2.9		2.9		
	I <sub>OH</sub> = -50 μA	4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
Voн	I <sub>OH</sub> = -4 mA	3 V	2.58			2.48		2.48		V
	[	4.5 V	3.94			3.8		3.8		
	$I_{OL} = -24 \text{ mA}$		4.94			4.8	W	4.8		
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V				3.85	'VIR	3.85		
	I <sub>OL</sub> = 50 μA	3 V			0.1		0.1		0.1	
		4.5 V			0.1	4:	0.1		0.1	
		5.5 V			0.1	377	0.1		0.1	
VOL	I <sub>OL</sub> = 12 mA	3 V			0.36	<sup>7</sup> 0¿	0.44		0.44	V
		4.5 V			0.36	ď	0.44		0.44	
	I <sub>OL</sub> = 24 mA	5.5 V			0.36		0.44		0.44	
	I <sub>OL</sub> = 75 mA <sup>†</sup>	5.5 V					1.65		1.65	
lį	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	μΑ
loz	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5		±5	μΑ
ICC	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		80		80	μΑ
C <sub>i</sub>	$V_I = V_{CC}$ or GND	5 V		3						pF
Co	V <sub>O</sub> = V <sub>CC</sub> or GND	5 V		11						pF

<sup>†</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

# timing requirements over recommended operating free-air temperature range, $V_{CC}$ = 3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

			T <sub>A</sub> = 25°C		<sub>A</sub> = 25°C 54AC16823		74AC16823		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency		0	60	0	60	0	60	MHz
t <sub>W</sub>	Pulse duration	CLR low	3.3		3.3	151	3.3		ns
	ruise duration	CLK high or low	8.4		8.4	PEL	8.4		
		CLR inactive	0.5		0.5	0	0.5		
t <sub>su</sub>	Setup time before CLK↑	Data	7.2		7.2		7.2		ns
		CLKEN low	5.8		5.8		5.8		
	Hold time after CLK↑	Data	0		0		0		ns
th	HOID THE AIRE CENT	CLKEN high or low	1		1		1		

# timing requirements over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

			T <sub>A</sub> = 25°C		54AC16823		74AC16823		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency		0	115	0	115	0	115	MHz
t <sub>w</sub>	Pulse duration	CLR low	3.3		3.3	EV	3.3		ns
	ruise dui attori	CLK high or low	4.4		4.4	EL	4.4		115
		CLR inactive	0.6		0.6	0	0.6		
t <sub>su</sub>	Setup time before CLK↑	Data	5		5		5		ns
		CLKEN low	4.2		4.2		4.2		
	Hold time after CLK↑	Data	1.3		21.3		1.3		ns
t <sub>h</sub>	HOIG LITTE AILET CLN	CLKEN high or low	1.4	·	1.4		1.4		

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	T,	T <sub>A</sub> = 25°C		54AC16823		74AC16823		UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
f <sub>max</sub>			60			60	-	60		MHz
<sup>t</sup> PLH	CLK	Q	3.9	13.8	16.8	3.9	18.8	3.9	18.8	ns
<sup>t</sup> PHL		Q	4.7	14.5	17.3	4.7	18.9	4.7	18.9	115
t <sub>PHL</sub>	CLR	Q	4	12.4	14.9	4	16.2	4	16.2	ns
<sup>t</sup> PZH	<del></del>	Q	3	11.1	14	3)	15.4	3	15.4	ns
<sup>t</sup> PZL	ŌĒ	ά	4.3	15	18.7	4.3	20.8	4.3	20.8	115
<sup>t</sup> PHZ	ŌĒ	Q	4.5	8.5	10.4	4.5	11.2	4.5	11.2	ns
<sup>t</sup> PLZ	OE .	γ	3.9	7.7	9.3	3.9	10.3	3.9	10.3	115

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

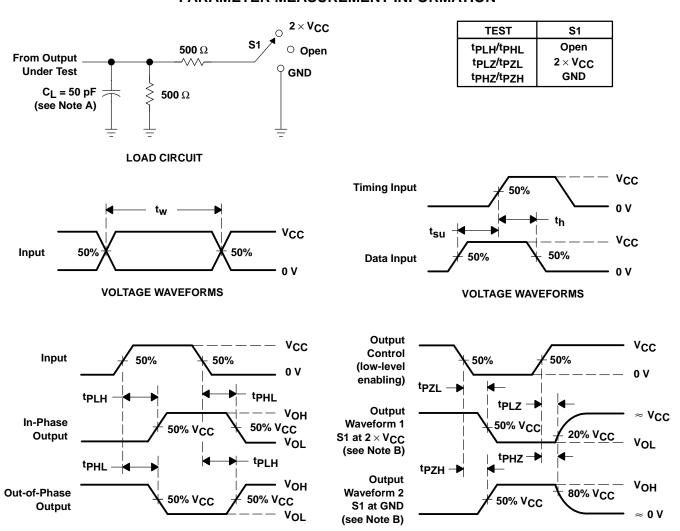
PARAMETER	FROM	то	T,	T <sub>A</sub> = 25°C		54AC16823		74AC16823		UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	ONII
f <sub>max</sub>			115			115		115		MHz
<sup>t</sup> PLH	CLK	Q	3.1	7.8	10.6	3.1	12	3.1	12	ns
t <sub>PHL</sub>		Q	3.9	8.6	11.4	3.9	12.7	3.9	12.7	115
t <sub>PHL</sub>	CLR	Q	3.2	7.4	9.9	3.2	2 11	3.2	11	ns
<sup>t</sup> PZH	ŌĒ	Q	2.2	6.1	8.6	2.2	9.7	2.2	9.7	ns
t <sub>PZL</sub>	OE	<sup>Q</sup>	3	7.4	10.6	33	11.8	3	11.8	115
t <sub>PHZ</sub>	ŌĒ	Q	4.2	6.8	8.7	4.2	9.3	4.2	9.3	ns
tPLZ	OE .	Q	3.7	6.2	7.8	3.7	8.6	3.7	8.6	115

## operating characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

		PARAMETER		TEST CONDITIONS	TYP	UNIT
Γ	<b>с</b> .	Power dissipation canaditance per flip flep	Outputs enabled	C1 = 50 pE f = 1 MHz	36	nE
C <sub>pd</sub>	Power dissipation capacitance per flip-flop	Outputs disabled	$C_L = 50 \text{ pF},  f = 1 \text{ MHz}$	18	pF	



#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

**VOLTAGE WAVEFORMS** 

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

**VOLTAGE WAVEFORMS** 

- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f = 3 \text{ ns}$ ,  $t_f = 3 \text{ ns}$ .
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



#### **IMPORTANT NOTICE**

Texas Instruments (TI) reserves the right to make changes to its products or to discontinue any semiconductor product or service without notice, and advises its customers to obtain the latest version of relevant information to verify, before placing orders, that the information being relied on is current.

TI warrants performance of its semiconductor products and related software to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

Certain applications using semiconductor products may involve potential risks of death, personal injury, or severe property or environmental damage ("Critical Applications").

TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS.

Inclusion of TI products in such applications is understood to be fully at the risk of the customer. Use of TI products in such applications requires the written approval of an appropriate TI officer. Questions concerning potential risk applications should be directed to TI through a local SC sales office.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards should be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein. Nor does TI warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used.

Copyright © 1996, Texas Instruments Incorporated